

Rheological properties			
Melt volume-flow rate	1.5	cm ³ /10min	ISO 1133
Temperature	190	-	
Load	2.16	0	
Moulding shrinkage, parallel	1.9		ISO 294-4, 2577
Moulding shrinkage, normal	1.7	%	ISO 294-4, 2577
Typical mechanical properties			
Tensile Modulus	1950	MPa	ISO 527-1/-2
Yield stress, 50mm/min	44	MPa	ISO 527-1/-2
Yield strain, 50mm/min	11	%	ISO 527-1/-2
Nominal strain at break		%	ISO 527-1/-2
Shear Modulus		MPa	ISO 6721
Charpy notched impact strength, 23°C	6.5	kJ/m²	ISO 179/1eA
Thermal properties			
Melting temperature, 10°C/min	166	°C	ISO 11357-1/-3
Temp. of deflection under load, 1.8 MPa	70	°C	ISO 75-1/-2
Vicat softening temperature, 50°C/h, 50N	135	°C	ISO 306
Electrical properties			
Volume resistivity	10	Ohm.m	IEC 62631-3-1
Surface resistivity	1000	Ohm	IEC 62631-3-2
Other properties			
Density	1380	kg/m³	ISO 1183
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Injection			
Drying Temperature	100 - 120		
Drying Time, Dehumidified Dryer	3 - 4		
Melt Temperature Optimum	200	°C	Internal

Additional information

/ additional information	
Injection molding	Standard reciprocating screw injection molding machines with a high compression screw (minimum 3:1 and preferably 4:1) and low back pressure (0.35 Mpa/50 PSI) are favored. Using a low compression screw (I.E. general purpose 2:1 compression ratio) can result in unmelted particles and poor melt homogeneity. Using a high back pressure to make up for a low compression ratio may lead to excessive shear heating and deterioration of the Hostaform® material.
	Melt Temperature: Preferred range 182-199 C (360-390 F). Melt temperature

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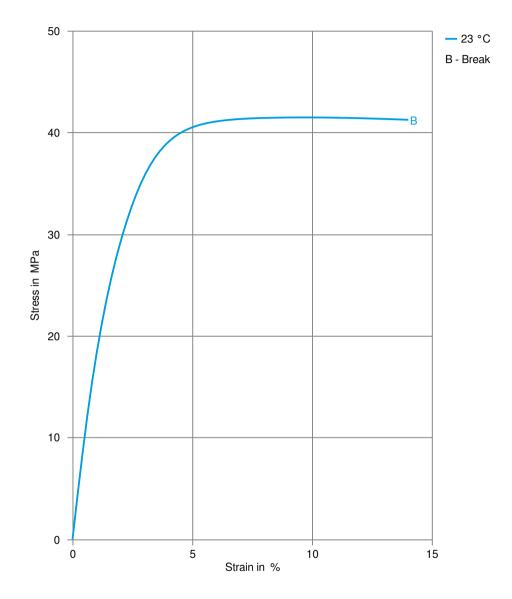


should never exceed 230 C (450 F).

Mold Surface Temperature: Preferred range 82-93 C (180-200 F) especially with wall thickness less than 1.5 mm (0.060 in.). May require mold temperature as high as 120 C (250 F) to reproduce mold surface or to assure minimal molded in stress. Wall thickness greater than 3mm (1/8 in.) may use a cooler (65 C/150 F) mold surface temperature and wall thickness over 6mm (1/4 in.) may use a cold mold surface down to 25 C (80 F). In general, mold surface temperatures lower than 82 C (180 F) may produce a hazy surface or a surface with flow lines, pits and other included defects.

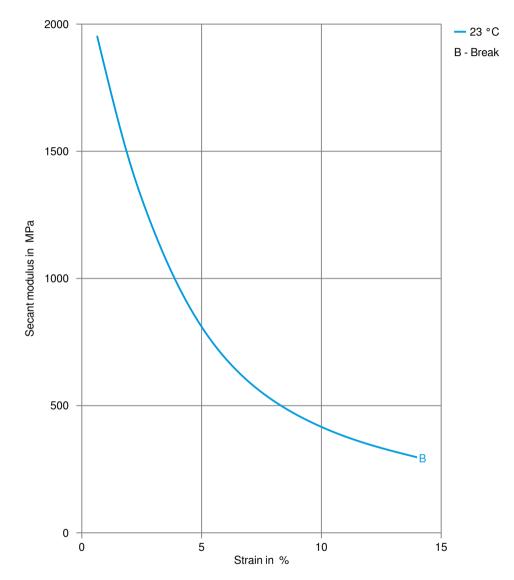
Stress-strain







Secant modulus-strain





Processing Texts	
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Injection molding Preprocessing	Drying is highly recommended for conductive carbon based ESD grades of Hostaform®. Excessive moisture can lead to splay (silver streaking) in molded parts. For better uniformity in molding especially when using regrind or material that has been stored in containers open to the atmosphere, recommended drying conditions are 80 C (180 F) for 3 hours. Desiccant hopper dryers are not required. Maximum water content = 0.35%
Injection molding Postprocessing	Postprocessing conditioning and moisturizing are not required. It may be necessary to fixture large or complicated parts with varying wall thickness to prevent warpage while cooling to ambient temperature.

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